# Low-Voltage CMOS Octal Transceiver

# With 5 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The 74LVC245A is a high performance, non–inverting octal transceiver operating from a 1.2 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V<sub>I</sub> specification of 5.5 V allows 74LVC245A inputs to be safely driven from 5 V devices if V<sub>CC</sub> is less than 5.0 V. The 74LVC245A is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24 mA at both A and B ports. The Transmit/Receive  $(T/\overline{R})$  input determines the direction of data flow through the bi–directional transceiver. Transmit (active–HIGH) enables data from A ports to B ports; Receive (active–LOW) enables data from B to A ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a HIGH Z condition.

#### **Features**

- Designed for 1.2 to 3.6 V V<sub>CC</sub> Operation
- 5 V Tolerant Interface Capability with 5 V TTL Logic
- Supports Live Insertion and Withdrawal
- $I_{OFF}$  Specification Guarantees High Impedance When  $V_{CC} = 0 \text{ V}$
- 24 mA Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μA)
   Substantially Reduces System Power Requirements
- ESD Performance: Human Body Model >2000 V Machine Model >200 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



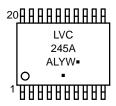
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#### MARKING DIAGRAM



TSSOP-20 DT SUFFIX CASE 948E



A = Assembly Location

L = Wafer Lot Y = Year W = Work Week ■ Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

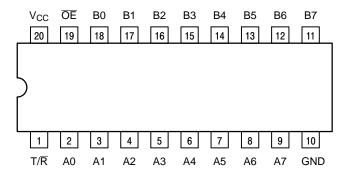


Figure 1. Pinout (Top View)

#### **PIN NAMES**

PINS	FUNCTION			
ŌĒ	OE Output Enable Input			
T/R	Transmit/Receive Input			
A0-A7	Side A 3-State Inputs or 3-State Outputs			
B0-B7	Side B 3-State Inputs or 3-State Outputs			

#### **TRUTH TABLE**

INF	PUTS	OPERATING MODE		
ŌĒ	T/R	Non-Inverting		
L	L	B Data to A Bus		
L	Н	A Data to B Bus		
Н	Х	Z		

H = High Voltage Level

L = Low Voltage Level Z = High Impedance State

X = High or Low Voltage Level and Transitions are Acceptable For I<sub>CC</sub> reasons, Do Not Float Inputs

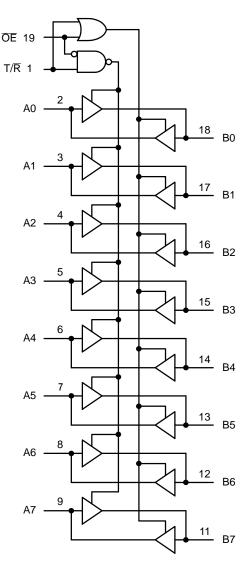


Figure 2. Logic Diagram

#### **MAXIMUM RATINGS**

Symbol	Parameter	Condition	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +6.5	V
VI	DC Input Voltage		$-0.5 \le V_1 \le +6.5$	V
Vo	DC Output Voltage	Output in 3-State	$-0.5 \le V_O \le +6.5$	V
		Output in HIGH or LOW State (Note 1)	$-0.5 \le V_{O} \le V_{CC} + 0.5$	1
I <sub>IK</sub>	DC Input Diode Current	V <sub>I</sub> < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>O</sub> < GND	-50	mA
		V <sub>O</sub> > V <sub>CC</sub>	+50	mA
ΙO	DC Output Source/Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin		±100	mA
$I_{GND}$	DC Ground Current Per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		T <sub>L</sub> = 260	°C
TJ	Junction Temperature Under Bias		T <sub>J</sub> = 135	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)		110.7	°C/W
MSL	Moisture Sensitivity	Level 1		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter			Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating Functional	1.65 1.2		3.6 3.6	V
VI	Input Voltage		0		5.5	V
V <sub>O</sub>	Output Voltage	HIGH or LOW State 3-State	0 0		V <sub>CC</sub> 5.5	V
ГОН	HIGH Level Output Current	V <sub>CC</sub> = 3.0 V - 3.6 V V <sub>CC</sub> = 2.7 V - 3.0 V			-24 -12	mA
I <sub>OL</sub>	LOW Level Output Current	V <sub>CC</sub> = 3.0 V - 3.6 V V <sub>CC</sub> = 2.7 V - 3.0 V			24 12	mA
T <sub>A</sub>	Operating Free-Air Temperature		-40		+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 1.2 \text{ to } 2.7 \text{ V}$ $V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$	0 0		20 10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

<sup>1.</sup> I<sub>O</sub> absolute maximum rating must be observed.

<sup>2.</sup> Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

#### DC ELECTRICAL CHARACTERISTICS

				40 to +85°	С	-4	0 to +125	°C	
Symbol	Parameter	Conditions	Min	Typ (Note 3)	Max	Min	Typ (Note 3)	Max	Unit
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 1.2 V	1.08	_	-	1.08	_	-	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 x V <sub>CC</sub>	-	-	0.65 x V <sub>CC</sub>	_	_	
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	_	-	1.7	_	-	
		V <sub>CC</sub> = 2.7 V to 3.6 V	2.0	_	-	2.0	_	-	
$V_{IL}$	LOW-level input voltage	V <sub>CC</sub> = 1.2 V	-	_	0.12	-	_	0.12	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	_	0.35 x V <sub>CC</sub>	-	_	0.35 x V <sub>CC</sub>	
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	_	0.7	-	_	0.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V	-	-	0.8	-	-	0.8	
V <sub>OH</sub>	HIGH-level output voltage	$V_I = V_{IH}$ or	· V <sub>IL</sub>	-		-	_	-	V
		$I_O = -100 \mu A;$ $V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	V <sub>CC</sub> - 0.2	_	_	V <sub>CC</sub> - 0.3	_	-	
		$I_O = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	_	-	1.05	_	-	
		$I_O = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.8	_	_	1.65	_	_	
		$I_{O} = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	_	_	2.05	_	_	
		$I_{O} = -18 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	_	_	2.25	_	-	
		$I_O = -24$ mA; $V_{CC} = 3.0$ V	2.2	_	_	2.0	_	-	
$V_{OL}$	LOW-level output voltage	$V_{I} = V_{IH}$ or	· V <sub>IL</sub>			_	_	-	V
		$I_O = 100 \mu A;$ $V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	_	_	0.2	_	_	0.3	
		$I_O = 4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	_	_	0.45	_	_	0.65	
		$I_{O}$ = 8 mA; $V_{CC}$ = 2.3 V	-	_	0.6	_	_	0.8	
		$I_{O}$ = 12 mA; $V_{CC}$ = 2.7 V	-	-	0.4	-	_	0.6	
		$I_{O}$ = 24 mA; $V_{CC}$ = 3.0 V	-	-	0.55	-	_	0.8	
I <sub>I</sub>	Input leakage current	$V_I = 5.5 \text{ V or GND}$ $V_{CC} = 3.6 \text{ V}$	-	±0.1	±5	-	±0.1	±20	μΑ
l <sub>OZ</sub>	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ ; $V_O = 5.5$ V or GND; $V_{CC} = 3.6$ V	_	±0.1	±5	_	±0.1	±20	μΑ
I <sub>OFF</sub>	Power-off leakage current	$V_I$ or $V_O = 5.5$ V; $V_{CC} = 0$ V	_	±0.1	±10	_	±0.1	±20	μΑ
I <sub>CC</sub>	Supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 3.6 \text{ V}$	-	0.1	10	-	0.1	40	μΑ
Icc	Additional supply current	per input pin; $V_I = V_{CC} - 0.6 \text{ V}$ ; $I_O = 0 \text{ A}$ ; $V_{CC} = 2.7 \text{ V}$ to 3.6 V	-	5	500	_	5	5000	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. All typical values are measured at  $T_A = 25^{\circ}C$  and  $V_{CC} = 3.3 \text{ V}$ , unless stated otherwise.

#### AC ELECTRICAL CHARACTERISTICS ( $t_R = t_F = 2.5 \text{ ns}$ )

			−40 to +85°C		-4	10 to +125°	,C		
Symbol	Parameter	Conditions	Min	Typ (Note 4)	Max	Min	Typ (Note 4)	Max	Unit
t <sub>pd</sub>	Propagation Delay (Note 5)	V <sub>CC</sub> = 1.2 V	-	17.0	-	-	-	-	ns
	An to Bn, Bn to An	V <sub>CC</sub> = 1.65 V to 1.95 V	1.5	6.5	14.6	1.0	_	16.9	
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	3.4	7.6	1.0	_	8.7	
		V <sub>CC</sub> = 2.7 V	1.0	3.4	7.3	1.0	-	9.5	
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	1.0	2.9	6.3	1.0	-	8.0	
t <sub>en</sub>	Enable Time (Note 6)  OE to An, Bn	V <sub>CC</sub> = 1.2 V	-	22.0	-	-	-	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	8.3	19.5	1.0	_	22.5	
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	4.6	10.7	1.0	_	12.4	
		V <sub>CC</sub> = 2.7 V	1.0	4.8	9.5	0.5	-	12.0	
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	3.7	8.5	0.5	-	11.0	
t <sub>dis</sub>	Disable Time (Note 7)	V <sub>CC</sub> = 1.2 V	-	12.0	-	-	-	-	ns
	OE to An, Bn	V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	5.5	12.3	1.0	_	14.2	
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	3.1	7.1	1.0	-	8.2	
		V <sub>CC</sub> = 2.7 V	1.0	3.9	8.0	0.5	-	10.0	
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	3.6	7.0	0.5	-	9.0	
t <sub>sk(0)</sub>	Output Skew Time (Note 8)		_	_	1.0	_	-	1.5	ns

- 4. Typical values are measured at  $T_A$  = 25°C and  $V_{CC}$  = 3.3 V, unless stated otherwise.
- t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.
   t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.
   t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.

- 8. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

#### **DYNAMIC SWITCHING CHARACTERISTICS**

			T <sub>A</sub> = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 9)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		0.8 0.6		V V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 9)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		-0.8 -0.6		V

<sup>9.</sup> Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

#### **CAPACITIVE CHARACTERISTICS**

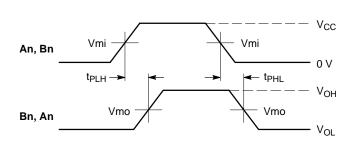
Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance (OE, T/R)	Input Capacitance ( $\overline{OE}$ , T/ $\overline{R}$ ) $V_{CC} = 3.3 \text{ V}$ , $V_I = 0 \text{ V or } V_{CC}$		pF
C <sub>I/O</sub>	Input/Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}$	10.0	pF
C <sub>PD</sub> Power Dissipation Capacitance		Per input; V <sub>I</sub> = GND or V	CC	pF
	(Note 10)	V <sub>CC</sub> = 1.65 V to 1.95 V	7.7	
		V <sub>CC</sub> = 2.3 V to 2.7 V	11.3	
		V <sub>CC</sub> = 3.0 V to 3.6 V	14.4	

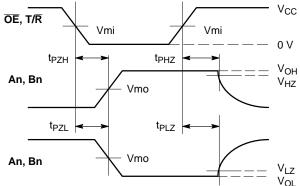
<sup>10.</sup>  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

V<sub>CC</sub> = supply voltage in Volts N = number of outputs switching

 $P_D = C_{PD} \times V_{CC}^2 \times \text{fi x N} + \Sigma (C_L \times V_{CC}^2 \times \text{fo}) \text{ where:}$  fi = input frequency in MHz; fo = output frequency in MHz  $C_L = \text{output load capacitance in pF}$ 

 $<sup>\</sup>Sigma(C_L \times V_{CC}^2 \times fo) = sum of the outputs.$ 





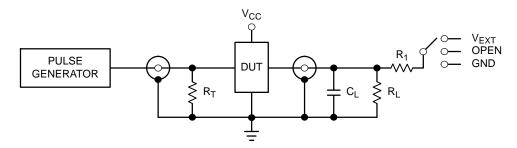
**WAVEFORM 1 - PROPAGATION DELAYS** 

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 

WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES  $t_R = t_F = 2.5 \text{ ns}, \, 10\% \text{ to } 90\%; \, f = 1 \text{ MHz}; \, t_W = 500 \text{ ns}$ 

Figure 3. AC Waveforms

	V <sub>CC</sub>							
Symbol	1.2 V	1.8 V ± 0.15 V	2.5 V ± 0.2 V	2.7 V	3.3 V ± 0.3 V			
V <sub>I</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	2.7 V	2.7 V			
Vmi	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	1.5 V	1.5 V			
Vmo	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	1.5 V	1.5 V			
$V_{HZ}$	V <sub>OL</sub> + 0.15 V	V <sub>OL</sub> + 0.15 V	V <sub>OL</sub> + 0.15 V	V <sub>OL</sub> + 0.3 V	V <sub>OL</sub> + 0.3 V			
$V_{LZ}$	V <sub>OH</sub> – 0.15 V	V <sub>OH</sub> – 0.15 V	V <sub>OH</sub> – 0.15 V	V <sub>OH</sub> – 0.3 V	V <sub>OH</sub> – 0.3 V			



 $C_L$  includes jig and probe capacitance  $R_T$  =  $Z_{OUT}$  of pulse generator (typically 50 Q)  $R_1$  =  $R_L$ 

Supply Voltage	lnı	out	Load		V <sub>EXT</sub>		
V <sub>CC</sub> (V)	V <sub>I</sub>	t <sub>r</sub> , t <sub>f</sub>	CL	$R_L$	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PLZ</sub> , t <sub>PZL</sub>	t <sub>PHZ</sub> , t <sub>PZH</sub>
1.2	V <sub>CC</sub>	≤ 2 ns	30 pF	1 kQ	Open	2 x V <sub>CC</sub>	GND
1.65 – 1.95	V <sub>CC</sub>	≤ 2 ns	30 pF	1 kQ	Open	2 x V <sub>CC</sub>	GND
2.3 – 2.7	V <sub>CC</sub>	≤ 2 ns	30 pF	500 Q	Open	2 x V <sub>CC</sub>	GND
2.7	2.7 V	≤ 2.5 ns	50 pF	500 Q	Open	2 x V <sub>CC</sub>	GND
3.0 – 3.6	2.7 V	≤ 2.5 ns	50 pF	500 Q	Open	2 x V <sub>CC</sub>	GND

Figure 4. Test Circuit

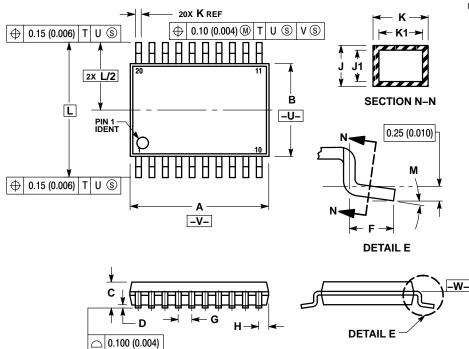
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
74LVC245ADTR2G	TSSOP-20 (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

#### TSSOP-20 CASE 948E-02 **ISSUE C**



-T- SEATING PLANE

- NOTES:

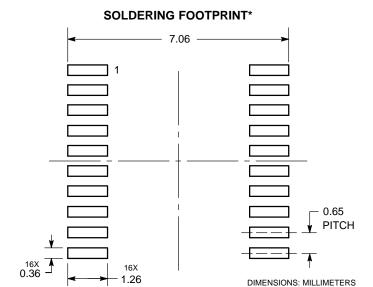
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION:
  MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE

  - 5. DIMENSION K DOES NOT INCLUDE
    DAMBAR PROTRUSION. ALLOWABLE
    DAMBAR PROTRUSION SHALL BE 0.08
    (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL
  - CONDITION.

    6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

    7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE —W.—.

	MALL LIN	IETERS		HES
				_
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	BSC
М	0°	8°	0°	8°



<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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